NOTICE OF REVISION (NOR) 1. DATE (YYMMDD) THIS REVISION DESCRIBED BELOW HAS BEEN AUTHORIZED FOR THE DOCUMENT LISTED. 97-03-21							Form Approved OMB No. 0704-0188	
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for Information Of Paperwork Reduct PLEASE DO NOT R CONTRACTING O	perations an ion Project ((RETURN YOL OFFICER FO	d Reports, 1215 Jefferson)704-0188), Washington, D JR COMPLETED FORM TO R THE CONTRACT/ PROC	Davis Highway, Suite C 20503. EITHER OF THES EURING ACTIVITY N	ADDRESSED. RETURN C MBER LISTED IN ITEM 2 C	4302, and to the Office of Mar COMPLETED FORM TO THE C OF THIS FORM.	agement and Budget,	3. DODAAC	
4. ORIGINATO	OR		b. ADDRESS (Defense Sup	b. ADDRESS (Street, City, State, Zip Code) Defense Supply Center Columbus			6. NOR NO. 5962-R241-97	
a. TYPED NAI <i>Last)</i>	ME <i>(First,</i>	Middle Initial,	Columbus, O	H 43216-5000		7. CAGE CODE 67268	8. DOCUMENT NO. 5962-88658	
9. TITLE OF D MICROCIR	DOCUME CUIT, LII	NT NEAR, 12-BIT A/D	CONVERTER,	HYBRID	10. REVISION LETT	ER	11. ECP NO.	
					a. CURRENT A	b. NEW B	N/A	
12. CONFIGU All	RATION	ITEM (OR SYSTEM) TO WHICH EC	CP APPLIES	•	1		
13. DESCRIP	TION OF	REVISION						
Sheet 1: R Revis Revis Sheet 8: Fl Revis Sheet 9: Fl conne Revis Sheet 10: F Revis	 Sheet 1: Revisions Itr column; add "B". Revisions description column; add "Ghanges in accordance with NOR 5962-R241-97". Revisions date column; add "97-03-21". Revision level block; change "A" to "B". Rev status of sheets; for sheets 1, 8, 9, and 10, change "A" to "B". Sheet 8: FIGURE 2 Terminal connections, pins 22 and 23, change "SERIAL OUT" and "SERIAL OUT" to "NC" and "NC", respectively. Revision level block; add "A". Sheet 9: FIGURE 3, Logic diagram, delete the output line from the 12-bit SAR that connects directly to pin 23 and the NOT gate connecting to pin 22. Revision level block; add "A". Sheet 10: FIGURE 4, Timing diagram, delete the timing waveform for the "SERIAL OUT" in its entirety. Revision level block; add "A". 							
14. THIS SEC	TION FO	R GOVERNMENT U	JSE ONLY					
a. (X one)	Х	(1) Existing docume	ent supplemented	d by the NOR may be	used in manufacture.			
		(2) Revised docum	ent must be rece	ived before manufactu	rer may incorporate this	change.		
		(3) Custodian of ma	aster document s	hall make above revisi	ion and furnish revised o	document.		
b. ACTIVITY A	UTHORI	ZED TO APPROVE	CHANGE FOR	GOVERNMENT	c. TYPED NAME (Fir	st, Middle Initial, Last)		
DSCC-VAT					Kendall A. Cottongir	n		
d. TITLE Team Chief, Electronic Co	omponent	s Team		e. SIGNATURE Kendall A. Cottong	im		f. DATE SIGNED (YYMMDD) 97-03-21	
15a. ACTIVIT	Y ACCON	IPLISHING REVISIO	N	b. REVISION COMF	PLETED (Signature)		c. DATE SIGNED (YYMMDD)	
DSCC-VAT				Gary Zahn			97-03-21	
DD Form 1695, APR 92			Previous editions are	e obsolete.				

REVISIONS																				
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THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE			APP Gre	ROVE g A. L	D BY ude				MIC CON	CROC IVER	IRCU TER	JITS , HY	S, LI BRID	NEA)	AR,	12-1	BIT	A/D		
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DESC FORM 193

JUL 91

DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

5962-E130

1. SCOPE

1.1 <u>Scope</u>. This drawing describes device requirements for class H hybrid microcircuits to be processed in accordance with MIL-H-38534.

1.2 Part or Identifying Number (PIN). The complete PIN shall be as shown in the following example:

<u>5962-88658</u>	01		<u>X</u>	<u>X</u>	
*	*		*	*	
*	*		*	*	
* Drawing number	*	. <u> </u>	* Case outline	*	
Drawing humber	(See 1.2.1)		(See 1.2.2)	MIL-H-38534	
1.2.1 <u>Device type(s)</u> . The de	vice type(s) shall identify the c	ircuit fund	ction as follows:		
Device type	Generic number		Circuit functio	<u>n</u>	
01	AD578SD	A/D c	onverter, 12 bit, high	speed	
02 03	AD578TD AD578ZSD	A/D c A/D c	onverter, 12 bit, nign onverter, 12 bit, high	speed	
04	AD578ZTD	A/D c	onverter, 12 bit, high	speed	
1.2.2 <u>Case outline(s)</u> . The ca	ase outline(s) shall be as desig	nated in a	appendix C of MIL-N	I-38510, and as follows:	
Outline letter			Case outline		
Х	See figure 1, (32-I	lead, 1.64	10" x .605" x .280"), o	dual-in-line package	
1.3 Absolute maximum rating	<u>IS</u> .				
Supply voltages (±VCC)				. ±18 V dc	
Logic supply voltage (+VDD)				. +7 V dc	
Analog inputs (pins 27 and 28	3)			. ±25 V dc	
Storage temperature range				-65°C to +150°C	
Lead temperature (soldering,	10 seconds)			. +300°C	
Thermal resistance:	,				
Junction-to-case (Θ JC).				. 8°C/W	
Junction-to-ambient (OJA)				. 25°C/W	
Junction temperature (1)				. +1/5°C	
1.4 <u>Recommended operating</u>	<u>conditions</u> .				
Supply voltage range (±VCC)	:				
Device types 01 and 02				. ±13.5 V dc to ±16.5 V d	c
Logic supply voltage range (+))	• • • • • • • •		$\pm 11.4 \text{ V dc to } \pm 12.6 \text{ V d}$ +4 75 V dc to +5 25 V d	C IC
Ambient operating temperatur	re range (TA)	· · · · · · · · · · ·		-55° C to $+125^{\circ}$ C	
2. APPLICABLE DOCUMEN	ITS				
2.1 Government specification	is and standard. Unless other	wise spec	ified, the following s	pecifications and	
standard of the issue listed in that is specified in the solicitation, form a p	ssue of the Department of Defe part of this drawing to the exten	ense Inde nt specifie	x of Specifications a d herein.	nd Standards	
SPECIFICATIONS					
MILITARY					
MIL-M-38510 - MIL-H-38534 - I	Microcircuits, General Specific Hybrid Microcircuits, General S	ation for.	on for.		
			SIZE		
			Α		5962-88658
	NICS SUPPLY CENTER			REVISION LEVEL	SHEET
DATION,	01110 40444			A	2
					<u> </u>
JUL 91					

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

(Copies of the specifications, and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

3.1 <u>Item requirements</u>. The individual item requirements shall be in accordance with MIL-H-38534 and as specified herein.

3.2 <u>Design, construction, and physical dimensions</u> The design, construction, and physical dimensions shall be as specified in MIL-H-38534 and herein.

3.2.1 <u>Case outline(s)</u>. The case outline(s) shall be in accordance with 1.2.2 and figure 1.

3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 2.

3.2.3 Logic diagram. The logic diagram shall be as specified on figure 3.

3.2.4 <u>Timing diagram</u>. Timing diagram shall be as specified on figure 4.

3.2.5 Digital output data. Digital output data shall be as specified on figure 5.

3.3 <u>Electrical performance characteristics</u> Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full specified operating temperature range.

3.4 <u>Electrical test requirements</u> The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

3.5 <u>Marking</u>. Marking shall be in accordance with MIL-H-38534. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in QML-38534 (see 6.6 herein).

3.6 <u>Manufacturer eligibility</u>. In addition to the general requirements of MIL-H-38534, the manufacturer of the part described herein shall submit for DESC-ECT review and approval electrical test data (variables format) on 22 devices from the initial quality conformance inspection group A lot sample, produced on the certified line, for each device type listed herein. The data should also include a summary of all parameters manually tested, and for those which, if any, are guaranteed.

3.7 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in QML-38534 (see 6.6 herein). The certificate of compliance submitted to DESC-ECT prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-H-38534 and the requirements herein.

3.8 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-H-38534 shall be provided with each lot of microcircuits delivered to this drawing.

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-H-38534.

	0175		
STANDARDIZED MILITARY DRAWING	A		5962-88658
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL A	SHEET 3

	*	*	*	*	*		*
Test	*Symbol	* Conditions <u>1</u> /	* Group A	*Device	*	Limits	*Unit
	*	* -55° C <u><</u> T _A <u><</u> +125° C	*subgroups	* types	*		*
	*	* unless otherwise specified	*	*	*	*	*
	*	*	*	*	* IVIIN	* Max	*
Coin orror	*		* 1	* * ΛΠ	* 0.25	* 10.25	* * 0/ /EQD
Gain enor	* V _{GE}	* 20 V bipolar	*	*	*	*	* 70/F3N
	*	* end-point electrical	* 1	* All	*-0.30	* +0.30	*
	*	*	*	*	*	*	*
	*	*	*	*	*	*	*
Gain drift	*V _{GD}	* 10 V unipolar,	* 2,3	* 01,03	* -50	* +50	* ppm/° C
	*	* 20 V bipolar	*	* 02,04	* -30	* +30	*
	*	*	*	*	*	*	*
	*	*	*	*	*	*	*
Unipolar offset	*V _{OSE}	* 10 V unipolar	* 1	* All	*-0.25	* +0.25	* %/FSR
error	*	*	*	*	*	*	*
	*	*	*	*	*	*	*
	*	*	*	*	*	*	*
Unipolar offset	*\/	* 10 V unipolar	* 2 2	* 01 02	* _15	* _15	* nnm/° ∩
	* V _{OSD}	*	* 2,3	* 02.04	* -10	* +10	
unit	*	*	*	* 02,04	*	*	*
	*	*	*	*	*	*	*
Bipolar offset	*Voor	* 20 V bipolar.	* 1	* All	*-0.25	* +0.25	* %/FSR
error	* USE	* end-point electrical	* 1	* All	*-0.30	* +0.30	*
0.101	*	*	*	*	*	*	*
	*	*	*	*	*	*	*
Bipolar offset drift	*V _{OSD}	* 20 V bipolar	* 2,3	* 01,03	* -25	* +25	_* ppm/° C
	*	*	*	* 02,04	* -20	* +20	*
	*	*	*	*	*	*	*
	*	*	*	*	*	*	*
Linearity error	*RA	* 10 V unipolar,	* 1	* All	*-0.50	* +0.50	* LSB
	*	* 20 V bipolar	*	*	*	*	*
	*	*	*	*	*	*	*
	*		* 0 0	* All	* 0.75	* + 0 75	*
	*	* 10 v unipolar, * 20 V bipolar	* 2,3	* All	*-0.75 *	* +0.75	*
	*	*	*	*	*	*	*
	*	*	*	*	*	*	*
Differential	*DNI	* 10 V unipolar.	* 1, 2, 3	* All	* -1.0	* +1.0	*
linearity	*	* 20 V bipolar	*	*	*	*	*
error	*	*	*	*	*	*	*
	*	*	*	*	*	*	*
	*	*	*	*	*	*	*
10 V reference	* V _{RE}	*	* 1	* All	* -100	* +100	* mV
error	*	*	*	*	*	*	*
	*	*	*	*	*	*	*
	*	*	* 2,3	* All	* -20	* +20	* ppm/°C
	*	*	*	*	*	*	*
	*	*	*	*	*	*	*
	* DCDD	* 2/	* 1 2 2	* ∆II	*-0 005	*10 005	* 0/_/0/\/
supply	*	<i>≝</i> ∗	*	*	*	*	* /0/ /0+ V
sensitivity	*	*	*	*	*	*	*
contractive	*	*	*	*	*	*	*
See footnotes at en	d of table.						

		TABLE I. Electrical performanc	e characteristics -	Continued.			
	*	*	*	*	*		*
Test	*Symbol	* Conditions <u>1</u> /	* Group A	*Device	*	Limits	*Unit
	*	* -55° C <u><</u> Τ _Α <u><</u> +125° C	*subgroups	* types	*		*
	*	* unless otherwise specified	*	*	*	*	*
	*	*	*	*	* Min	* Max	*
	*	*	*	*	*	*	*
±V _{cc} Power	* PSRR	* <u>2</u> /	* 1,2,3	* 01,02	*-0.005	*+0.005	* %/%±V _{CC}
supply	*	*	*	*	*	*	*
sensitivity	*	*	*	*	*	*	*
	*	*	*	*	*	*	*
±V _{cc} Power	* PSRR	* <u>2</u> /	* 1,2,3	* 03,04	*-0.007	*+0.007	*
supply	*	*	*	*	*	*	*
sensitivity	*	*	*	*	*	*	*
	*	*	*	*	*	*	*
Digital output	* V _{он}	* at -80 µА I _{он}	* 1,2,3	* All	* 2.4	*	* V dc
nigh drive	*	* 2/	*	*	*	*	*
	*	*	*	*	*	*	*
	*	*	*	*	*	*	*
Digital output	* V _{OL}	* at 3.2 mA I _{oL}	* 1,2,3	* All	*	* 0.4	*
low drive	*	* <u></u>	*	*	*	*	*
	*	т Ф	*	*	*	*	*
	* • •	* All bits on	* 1 0 0	* * *	*	* 150	* ~~ ^
+v _{DD} Supply	* +I _{DD}	* All bits off * 2/	* 1,2,3 *	* All	*	* 150	* MA *
urain	*	*	*	*	*	*	*
	*	*	*	*	*	*	*
	* _	* All hits on	* 1 2 3	* ΔII	*	* 8	*
drain	* CC	* 2/	*	*	*	*	*
arain	*	*	*	*	*	*	*
	*	*	*	*	*	*	*
-Vas Supply	* -	* All bits on	* 123	* All	*	* 35	*
drain	*	* 2/	*	*	*	*	*
	*	*	*	*	*	*	*
	*	*	*	*	*	*	*
Power dissipation	*P_	* T ₄ = +25° C	*	* All	*	* 715	* mW
	*	*	*	*	*	*	*
Conversion speed	* t _c	* 3/	* 9,10,11	* 01,03	*	* 6	* µs
	*	*	* 9,10,11	* 02,04	*	* 4.5	*
	*	*	*	*	*	*	*

 $\underline{1}' + V_{\text{DD}} = \pm 4.75 \text{ V to } \pm 5.25 \text{ V}; \\ \pm V_{\text{CC}} = \pm 13.5 \text{ V to } \pm 16.5 \text{ V for device types 01 and 02}; \\ \pm V_{\text{CC}} = \pm 11.4 \text{ V to } \pm 12.6 \text{ V for device types 03 and 04}.$

- 2/ Subgroups 2 and 3 shall be tested as part of device initial characterization and every 52 weeks thereafter. Subgroups 2 and 3 shall also be tested after all design and process changes and shall be guaranteed to the limits specified in table I for all lots not specifically tested. Subgroup 1 shall be tested with every lot.
- 3/ Subgroups 10 and 11 shall be tested as part of device initial characterization and after design and process changes. Parameter shall be guaranteed to the limits specified in table I for all lots not specifically tested.
 - 4.2 Screening. Screening shall be in accordance with MIL-H-38534. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.7 herein).
 - (2) T_A as specified in accordance with table I of method 1015 of MIL-STD-883.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

STANDARDIZED MILITARY DRAWING	SIZE A		5962-88658
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL A	SHEET 5



*	*		*		*	*
*	* Inch	es	* Millime	eters	*	*
*	*	*	*	*	*	*
* Symbol	* Min	* Max	* Min	* Max	* Notes	*
*	*	*	*	*	*	*
* A	*	* .280	*	* 7.11	*	*
*	*	*	*	*	*	*
* b	* .016	* .020	* 0.41	* 0.51	*	*
*	*	*	*	*	*	*
* b ₁	* .035	* .045	* 0.89	* 1.14	* 2	*
*	*	*	*	*	*	*
*	*	*	*	*	*	*
* C	* .009	* .012	* 0.23	* 0.30	*	*
*	*	*	*	*	*	*
* D	* 1.584	* 1.640	* 40.23	* 41.66	*	*
*	*	*	*	*	*	*
* E	* .580	* .605	* 14.73	* 15.37	*	*
*	*	*	*	*	*	*
* E₁	* .590	* .610	* 14.99	* 15.49	* 6	*
*	*	*	*	*	*	*
*	*		*		*	*
* е	* .100	BSC	* 2.54	BSC	* 4,7	*
*	*	*	*	*	*	*
* L	* .125	* .200	* 3.18	* 5.08	*	*
*	*	*	*	*	*	*
* L1	* .180	*	* 4.57	*	*	*
*	*	*	*	*	*	*
*	*	*	*	*	*	*
* Q	* .015	* .060	* 0.38	* 1.52	* 3	*
*	*	*	*	*	*	*
* S	*	* .098	*	* 2.49	* 5	*
*	*	*	*	*	*	*
* S₁	* .005	*	* 0.13	*	* 5	*
*	*	*	*	*	*	*

NOTES:

- 1. Index area; a notch or a lead one indentification mark is located adjacent to lead one.
- 2. The minimum limit for dimension b may be .023 inch (0.58 mm) for all four corner leads only.
- 3. Dimension Q shall be measured from the seating plane to the base plane.
- 4. The basic pin spacing is .100 inch (2.54 mm) between centerlines.
- 5. Applies to all four corners.
- 6. E_1 shall be measured at the centerline of the leads.
- 7. Thirty spaces.
- 8. Dimensions are in inches.
- 9. Metric equivalents are given for general information only.

FIGURE 1. Case outline X - Continued.

STANDARDIZED MILITARY DRAWING	SIZE A		5962-88658
DEFENSE ELECTRONICS SUPPLY CENTER		REVISION LEVEL	SHEET
DAYTON, OHIO 45444		A	7

*	Device types	* 01, 02, 03, and 04	k
*		*	×
*	Case outline	* X	×
*		*	*
*	Ferminal number	* Terminal symbol	*
*		*	*
*		*	*
*	1	* BIT 12	*
*	2	* BIT 11	4
*	3	* BIT 10	*
*	4	* BIT 9	4
*	5	* BIT 8	*
*	6	* BIT 7	4
*	1	* BIT 6	4
*	8	* BIT 5	4
*	9	* BIT 4	3
*	10	* BIT 0	1
* *	11	* BIT 4	1
~ ~	12	* <u>BIT 1</u>	1
*	13		r k
*	14		k
*	10		×
*	10		*
*	18		×
*	10		×
*	20	* FOC	×
*	21	* CONVERT START	×
*	22	* SERIAL OUT	×
*	23	* SERIAL OUT	×
*	24	* REF OUT	×
*	25	* GAIN (REF IN)	×
*	26	* BIPOLAR OFÉSET	×
*	27	* 10 V SPAN INPUT	×
*	28	* 20 V SPAN INPUT	×
*	29	* ZERO ADJ	k
*	30	* ANALOG GND	×
*	31	* +15 V	k
*	32	* -15 V	k
4		*	

FIGURE 2. Terminal connections.

STANDARDIZED MILITARY DRAWING	SIZE A		5962-88658
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DAYTON, OHIO 45444		A	8



EOC 100 ns-++ +- BIT 1								
BIT 2								
BIT 3								
BIT 4								
BIT 5								
BIT 6								
BIT 7								
BIT 8								
e TI8								
BIT 10								
BIT 11								
BIT 12								
SERIAL OUT B1 B2 B3 B4 B5 B6 B	7 88 89 810 811 813							
Clock: Internal: Connect clock out (18) to cl External: Connect external clock to c clock should be at least 30 minimum period, t _{MIN} of 100	Clock: Internal: Connect clock out (18) to clock in (19). External: Connect external clock to clock in (19), clock should be at least 30 percent duty cycle with minimum period, t _{MN} of 100 ns.							
Note: The rising edge of convert start and the LSB to one. The trailing	pulse resets the N edge initiates co	ISB to zero, nversion.						
FIGURE 4. <u>Ti</u>	ming diagram.							
	SIZE A		5962-88658					
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL A	SHEET 10					
		-	-					

 Analog input - volts (center of quantization interval) 		 Digital output code (binary for unipolar ranges; 			
*			* offset bi	nary for bipolar ranges)	*
*	*	*	*	*	×
* 0 to +10 V * Range *	* 0 to +20 V * Range *	*-5 V to +5 V * Range *	*-10 V to +10 V * Range *	* B1 B12 * (MSB) (LSB) *	* * (
*	*	*	*	*	×
* +9.9976 * +9.9952 * -	* +19.9951 * +19.9902 * -	* +4.9976 * +4.9952 * -	* +9.9951 * +9.9902 * -	*11111111111 *111111111111 * -	1 * 0 *
* _	* _	* _	* _	* -	*
* +5.0024 * +5.0000 * -	* +10.0049 * +10.0000 *	* +0.0024 * +0.0000	* +0.0049 * +0.0000 * -	* 1 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0)1 *)0 *
* _	* _	* _	* _	* _	×
* +0.0024 * +0.0000	* +0.0051 * +0.0000 *	* -4.9976 * -5.0000 *	* -9.9951 * -10.0000 *	* 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0)1 *)0 *

FIGURE 5. Digital output data.

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4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with MIL-H-38534 and as specified herein.

4.3.1 Group A inspection. Group A inspection shall be in accordance with MIL-H-38534 and as follows:

- a. Tests shall be as specified in table II herein.
- b. Subgroups 4, 5, 6, 7, and 8 shall be omitted.

4.3.2 Group B inspection. Group B inspection shall be in accordance with MIL-H-38534.

4.3.3 Group C inspection. Group C inspection shall be in accordance with MIL-H-38534 and as follows:

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.

(1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.7 herein).

- (2) T_A as specified in accordance with table I of method 1005 of MIL-STD-883.
- (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

* MIL-STD-883 test requirements * * *	 * Subgroups * (per method * 5008, group A * test table) 		* * *
*	*		*
*Interim electrical parameters	*	1	*
*	*		*
*	*		*
*Final electrical test	*	1*. 2. 3. 4.	*
* parameters	*	.,_,_,,,,	*
*	*		*
*	*		*
*Group A test requirements	*	1, 2, 3, 9,	*
*	*	10, 11	*
*	*	•	*
*Group C end-point electrical	*	1, 2, 3	*
* parameters	*	, , ,	*
*	*		*

TABLE II. Electrical test requirements.

* PDA applies to subgroup 1.

4.3.4 Group D inspection. Group D inspection shall be in accordance with MIL-H-38534.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-H-38534.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for original equipment design applications and logistic support of existing equipment.

6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).

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6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-ECT, telephone (513) 296-6047.

6.5 Comments. Comments on this drawing should be directed to DESC-ECT, Dayton, Ohio 45444, or telephone (513) 296-5374

6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in QML-38534. Additional sources will be added to QML-38534 as they become available. The vendors listed in QML-38534 have agreed to this drawing and a certificate of compliance (see 3.7 herein) has been submitted to and accepted by DESC-ECT.

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STANDARDIZED MILITARY DRAWING SOURCE APPROVAL BULLETIN

DATE: 9-11-20

Approved sources of supply for SMD 5962-88658 are listed below for immediate acquisition only and shall be added to QML-38534 during the next revision. QML-38534 will be revised to include the addition o deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DESC-ECT. This bulletin is superseded by the next dated revision of QML-38534.

			_
* Standardized	* Vendor	* Vendor	*
* military drawing	* CAGE	* similar	*
* PIN	* number	* PIN <u>1</u> /	*
*	*	*	*
*	*	*	*
* 5962-8865801XX	* 51640	*AD578SD/883B	*
*	*	*	*
* 5962-8865802XX	* 51640	*AD578TD/883B	*
*	*	*	*
* 5962-8865803XX	* 51640	*AD578ZSD/883B	*
*	*	*	*
* 5962-8865804XX	* 51640	*AD578ZTD/883B	*
*	*	*	*

 <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirement of this drawing.

Vendor CAGE number Vendor name and address

51640

Analog Devices Microelectronics Division 831 Woburn Street Wilmington, MA 01887

* The information contained herein is disseminated for convenience only and	*
* the Government assumes no liability whatsoever for any inaccuracies in this	*
* information bulletin.	*